



## Typical Bias Conditions

for an ambient Temperature of +25°C

Symbol	Pin No.	Parameter	Values	Unit
Vs	1	VS control voltage	-5 to 0	V
Vp	3	VP control voltage	0 to -5	V

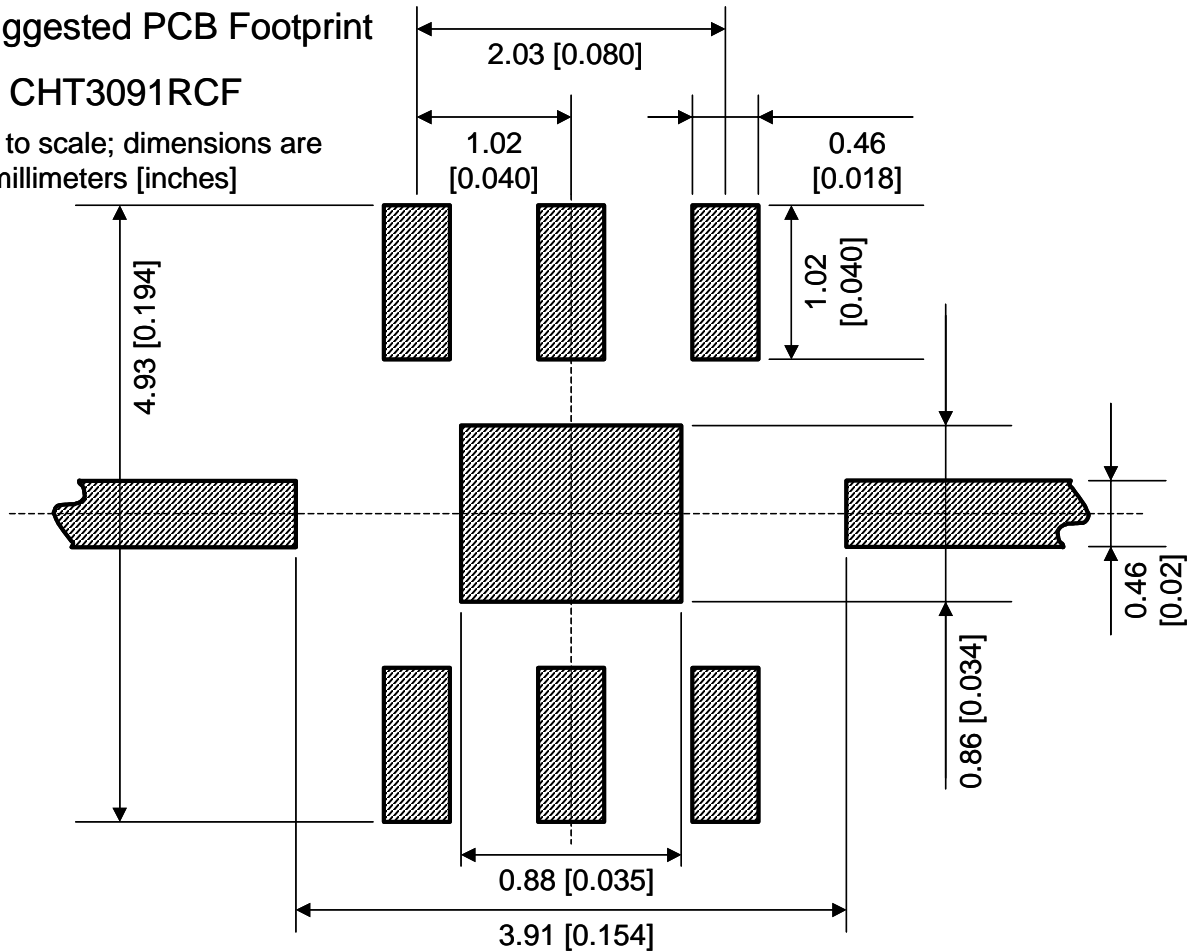
All other pins are not used for this device.

## Footprint

### Suggested PCB Footprint

#### for CHT3091RCF

not to scale; dimensions are in millimeters [inches]



## SMD mounting procedure

The SMD leadless package has been designed for high volume surface mount PCB assembly process. The dimensions and footprint required for the PCB (motherboard) are given in the drawings above.

For the mounting process standard techniques involving solder paste and a suitable reflow process can be used.

For further details, see application note AN0005.

## Ordering Information

SMD leadless package form : CHT3091RCF/24

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